

L Number	Hits	Search Text	DB	Time stamp
1	42	(chip IC die) with (power adj supply adj module)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/08/14 11:48
2	5	sasakura-takahiro.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/08/14 11:50
3	193	abe-seiichi.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/08/14 11:59
4	36	(electronic adj component) with ((power adj circuit) (power adj supply adj module))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/08/14 12:00
5	441	257/777,784,723,676,684.ccls. and power and (heat adj (sink plate slug element spreader))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/08/14 14:00
6	5552	(power adj supply) and (open\$4 recess\$4) and (heat adj (sink plate spreader element slug))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/08/14 14:03
7	1998	(power adj supply) and (open\$4 recess\$4) and (heat adj (sink plate spreader element slug)) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/08/14 14:03
9	153	(power adj supply) with (open\$4 recess\$4) and (heat adj (sink plate spreader element slug)) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/08/14 14:05
10	28	257/737-738,675,706,711-713.ccls. and (power adj supply) with (heat adj (sink plate element slug spreader))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/08/14 14:13
11	1060	(power adj supply) with (heat adj (sink plate element slug spreader))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/08/14 14:17
12	9621	(chip IC die) with (heat adj (sink plate element slug spreader))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/08/14 14:18
13	2022	(chip IC die) with (heat adj (sink plate element slug spreader)) and (bump ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/08/14 14:20
14	17	("4042539" "4740425" "4876588" "4914551" "5022968" "5028984" "5206792" "5208103" "5218215" "5262674" "5300158" "5343073" "5346765" "5367196" "5422788" "5591034" "5608267").PN.	USPAT	2003/08/14 14:23

15	12	("5397917" "5583378" "5724230" "5726493" "5796038" "5854511" "5866943" "5886408" "5909056" "5926371" "6020637" "6046499").PN.	USPAT	2003/08/14 14:33
-	8	(("20030052393") or ("5625221") or ("6252299") or ("5394010")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/08/13 19:34
-	81750	(power adj supply) and (chip die IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/08/13 19:36
-	637	(power adj supply) and (chip die IC) and stack and seal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/08/13 19:39
-	337	(power adj supply and module) and (chip die IC) and stack and seal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/08/13 19:49
-	6	257/777,784,723,676,684.ccls. and (power adj supply adj module)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/08/14 13:46
-	1	257/685-686,690-691.ccls. and (power adj supply adj module)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/08/13 19:59
-	0	20030047800.URPN.	USPAT	2003/08/13 19:53
-	5	257/737-738,675,706,711-713.ccls. and (power adj supply adj module)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/08/14 14:08
-	43	257/777,784,723,676,684.ccls. and (power adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/08/13 19:59
-	46	257/685-686,690-691.ccls. and (power adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/08/13 19:59
-	55	257/737-738,675,706,711-713.ccls. and (power adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/08/14 11:45